

AN 130:19574 HCA
TI Copper alloy having high stamping processability for
electronic applications
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SO Jpn. Kokai Tokkyo Koho, 8 pp.
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AB	The Cu alloy comprises Cr 0.1-0.4, Zr .gtoreq.0 and <0.2, rare earth metal 0.002-0.2, Pb and/or Bi 0.002-0.2 wt.% (in total), and Cu bal. and the alloy has crystd. substances and deposited substances with diam. <3 .mu.m and crystal grain size <20 .mu.m. Alternatively, the above Cu alloy may also contain 0.01-1.0 wt.% Sn, Mg, Ni, Ag, Zn, Si, and/or Mn in total. The Cu alloy has high strength and cond. and is useful for lead frames for semiconductor device such as integrated circuit or for heat medium such as terminals, connectors, contacts, and so on.				